

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the above-identified application:

1. (Currently Amended) An assembly for use in a chemical-mechanical apparatus, comprising:
 - a pad having an upper surface and having at least a first aperture therethrough;
 - a platen for supporting said pad, said platen having a top surface and at least a second aperture therethrough; and
 - a substantially transparent plug including at least a first section and at least a second section, the first section positioned substantially within the first aperture and having an end substantially flush with the upper surface of the pad, and the second section positioned substantially within the second aperture, the second section being partially hollow;
 - a light transmitting and receiving probe having a first portion and a second portion, the first portion having a diameter larger than the second portion, and the second portion being adapted to fit within the hollow section of the substantially transparent plug, the second portion having a top positioned flush with the top surface of the platen.
2. (Original) An assembly as set forth in claim 1 wherein the platen is constructed of a non-metallic material.
3. (Previously Presented) An assembly as set forth in claim 1 wherein the platen has a plurality of holes for delivering a slurry to the pad.

4. (Previously Presented) An assembly as set forth in claim 3 further comprising a manifold coupled to the platen for providing a slurry to the platen.

5. (Original) An assembly as set forth in claim 3 wherein the exterior of the platen is constructed of a non-metallic material.

6. (Original) An assembly as set forth in claim 4 wherein the exterior of the platen is constructed entirely of a non-metallic material.

7. (Original) An assembly as set forth in claim 4 wherein the exteriors of the platen and the manifold are constructed entirely of a non-metallic material.

8-13 Canceled

14. (Previously Presented) A chemical mechanical wafer processing apparatus comprising;

a polishing pad having a top surface;

a platen having a top surface for supporting the polishing pad,

a manifold for delivering a slurry to the platen,

an upper polishing module configured to position a workpiece substantially in contact with the polishing pad supported by the platen,

a light transmission medium for transmitting and receiving light to and from the workpiece, one end of the medium positioned flush with the top surface of the polishing pad prior to initiation of a polishing operation, the other end of the transmission medium having a hollow portion for receiving a light transmitting and receiving probe, the light transmitting and receiving probe having an end portion flush with the top of the platen.

15. (Original) An apparatus as set forth in claim 14 wherein the light transmission medium is used as a registration guide for positioning the pad on the platen.

16-20 Canceled